

Micro Commercial Components Corp.

Tin Whisker Test Report for SMD-Cu

Test Purpose: Inspect the performance of whisker growth Category: Copper base material with tin plating, plating thickness is 8~20um, heat treat method is 150°C annealing for 1 hour

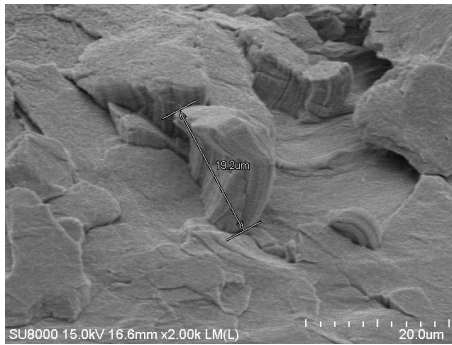
Test Standard: JESD201A

Test Items	Test Condition	Acceptance Criteria
TCT	-40°C~85°C, 10min soak, 2000cycles	≤50um
THT	30°C/60%RH, 4000Hrs	≤40um
HT&H	55°C/85%RH, 4000Hrs	≤40um

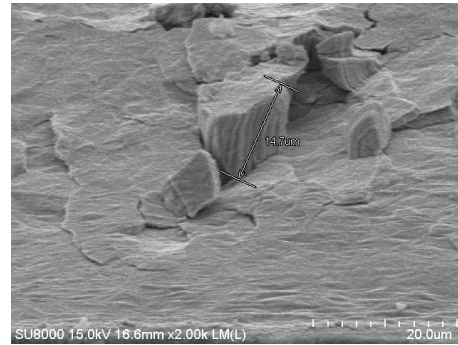
Package list:

SOT-23, SOT-23-3L, SOT-23-6L, SOT-223, SOT-89, DFN1006, DFN2020, DFN2030, SOP-8, DFN3030, DFN3333, DFN5060, TO-252, TO-263, TOLL-8L, TSSOP-8, MBS-1, SDB-1, TBS, MBS-1, LMBS-1, MBLS-1, TBSL, TBL, SMA, SMB, SMC, SMAE, DO-221AC, DO-218AB, SMPA, SME, SMG, SOD-123HE, SOD-123HE1, SOD-123, SOD-323, SOD-323FH, SOD-323HE, SOD-123FL, SOD-323FL, SOD-123HT

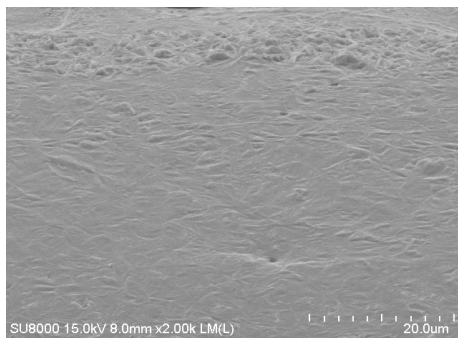
Test Results:



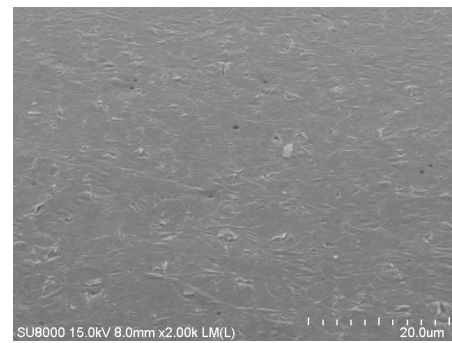
TCT 19.2um max



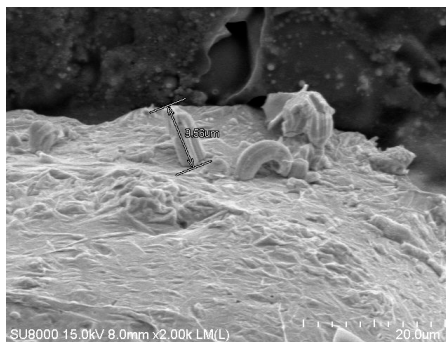
14.7um



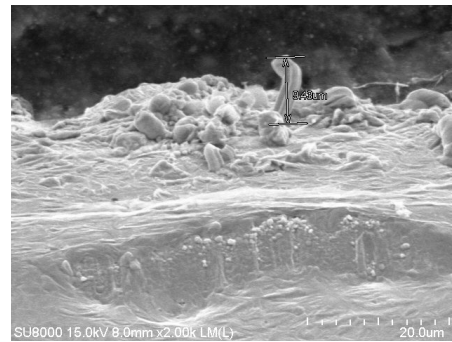
THT No Whisker



No Whisker



HT&T 9.56um max



9.43um

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Date: 2020-7-20

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